

EAST Search History

L9	34	8 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ not near2 parallel) same (substrate board bga pcb interposer tape insulat\$3 near1 layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:35
L10	8319	8 not (1 4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:11
L11	8319	10 not (1 4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:11
L12	27	11 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ not near2 parallel) same (substrate board bga pcb interposer tape insulat\$3 near1 layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:17
L13	0	("257685-733").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:12
L14	29327	(257/685-733).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:12
L15	24946	14 not (1 4 8)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:12
L16	105	15 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ not near2 parallel) same (substrate board bga pcb interposer tape insulat\$3 near1 layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:16

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L17	10261	(257/777-786).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:17
L18	5081	17 NOT (1 4 8 14)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:17
L19	38	18 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ not near2 parallel) same (substrate board bga pcb interposer tape insulat\$3 near1 layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:18
L20	38	18 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ not near2 parallel) same (substrate board bga pcb interposer tape insulat\$3 near1 layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:18
L21	306	(attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (diagonal\$3) same (substrate board bga pcb interposer tape insulat\$3 near1 layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:21
L22	29	21 and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:23
L23	124	21 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:24
L24	98	23 not 22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:33

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L25	1496	(438/108).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:34
L26	1430	25 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:34
L27	25	25 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ diagonal\$3 not near2 parallel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:41
L28	1533	(438/118).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:40
L29	35	28 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ diagonal\$3 not near2 parallel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:45
L30	0	29 not (1 4 8 14 25)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:46
L31	1095	(257/783).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:44
L32	801	(257/782).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:45

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L33	2	("0003132").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:45
L34	1670	31 32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:45
L35	35	34 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ diagonal\$3 not near2 parallel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:47
L36	9	35 not (1 4 8 14 25)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:47
L37	3579	(257/778-779).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:47
L38	67	37 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ diagonal\$3 not near2 parallel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:48
L39	30	38 not (1 4 8 14 25 35)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:48